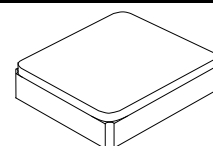


XTL2004

96.000000 MHz
Crystal Unit



SM2016-4

- Surface Mount Hermetic Package
- Excellent Reliability Performance
- Good Frequency Perturbation and Stability over temperature
- Ultra Miniature Package
- Moisture Sensitivity Level (MSL) : Level-1

Description and Applications:

Surface mount 2.0mmx1.6mm crystal unit for use in wireless communications devices, especially for a need of ultra miniature package for mobility.

Electrical Specifications:

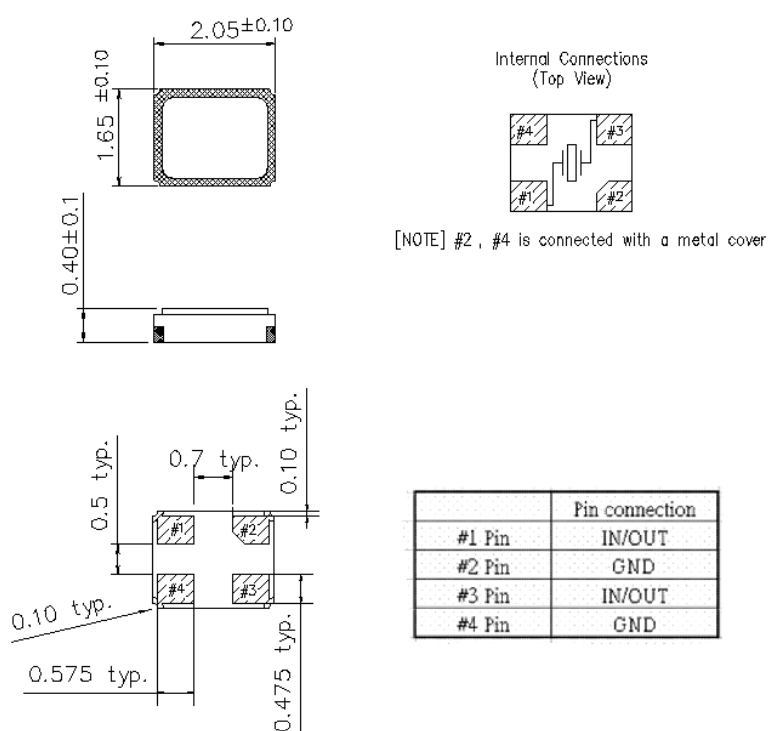
Electrical Specifications:

XTL2004	Specification			
Characteristic	Min	Nom	Max	Unit
Nominal Frequency		96.000000		MHz
Mode of Oscillation		Fundamental		°C
Storage Temperature Range	-40		105	°C
Operating Temperature Range	-40		105	°C
Initial frequency tolerance(25°C ± 3°C)(offset -30ppm)	-12		12	ppm
Frequency drift after reflow(After two reflows)	-2		2	ppm
Tolerance over temperature(-40°C to 105°C)	-16		16	ppm
Frequency perturbation(-40°C to 105°C)				ppm
Aging(Five years)				ppm
Equivalent Series Resistance (ESR)		8	20	Ω
Spurious mode series resistance	1100			Ω
Motional inductance	0.5	1.0	1.2	mH
Motional capacitance	2	2.7	4.2	fF
Shunt capacitance	0.5	1.0	1.2	pF
Load Capacitance (CL) (Measure by Saunders(S&A) Network Analyzer 250B)		9.9		pF
Nominal Drive Level	0.01	100	400	uW

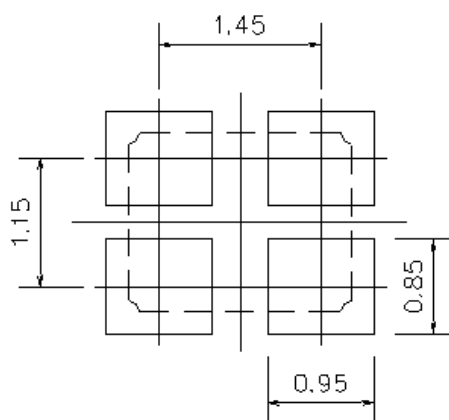
Insulation Resistance(DC 100V)	500			MR
Package size		2.0x1.6		mm ²
Package height			0.50	mm

Mechanical Dimensions (mm):

Base



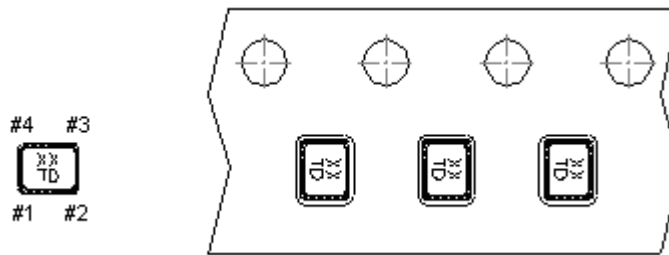
Recommended Land Pattern: (unit: mm)



Marking:

Line 1: XX; Frequency (96)

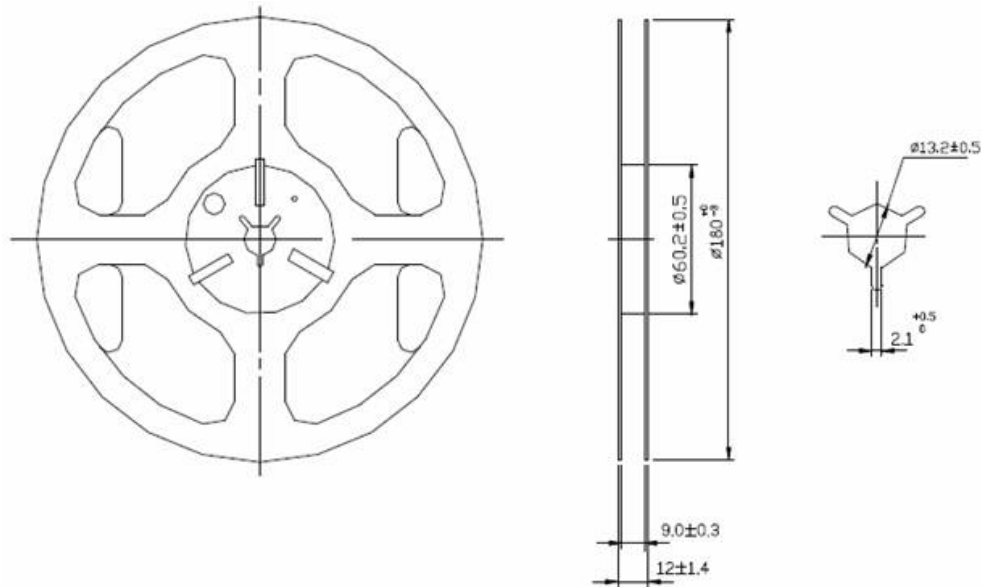
Line 2: T; Traceable Code + D; date Code of Year/Month



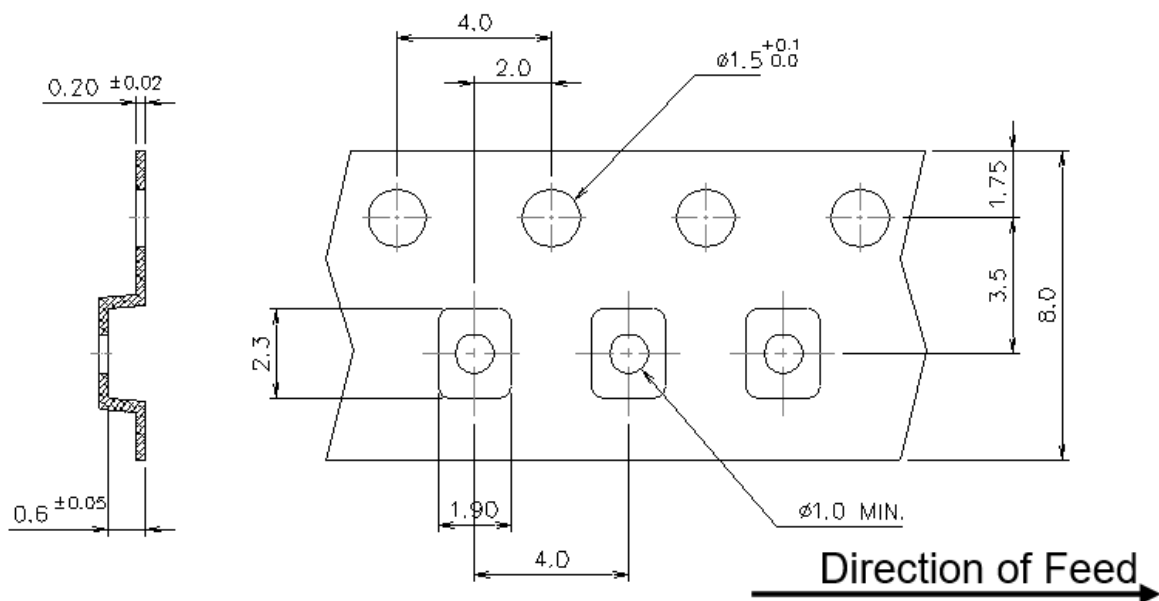
Date Code Table: Year/Month

Year/Month	1	2	3	4	5	6	7	8	9	10	11	12
2009	n	p	q	r	s	t	u	v	w	x	y	z
2010	A	B	C	D	E	F	G	H	J	K	L	M
2011	N	P	Q	R	S	T	U	V	W	X	Y	Z
2012	a	b	c	d	e	f	g	h	i	j	k	m
2013	n	p	q	r	s	t	u	v	w	x	y	z
2014	A	B	C	D	E	F	G	H	J	K	L	M
2015	N	P	Q	R	S	T	U	V	W	X	Y	Z
2016	a	b	c	d	e	f	g	h	i	j	k	m
2017	n	p	q	r	s	t	u	v	w	x	y	z
2018	A	B	C	D	E	F	G	H	J	K	L	M
2019	N	P	Q	R	S	T	U	V	W	X	Y	Z
2020	a	b	c	d	e	f	g	h	i	j	k	m
2021	n	p	q	r	s	t	u	v	w	x	y	z

Reel Dimensions (mm):



Tape Dimensions (mm):

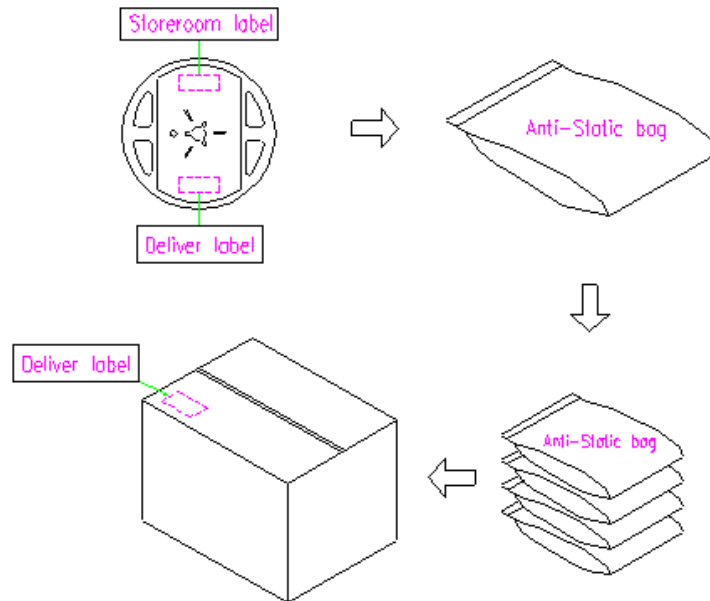


[NOTE]:

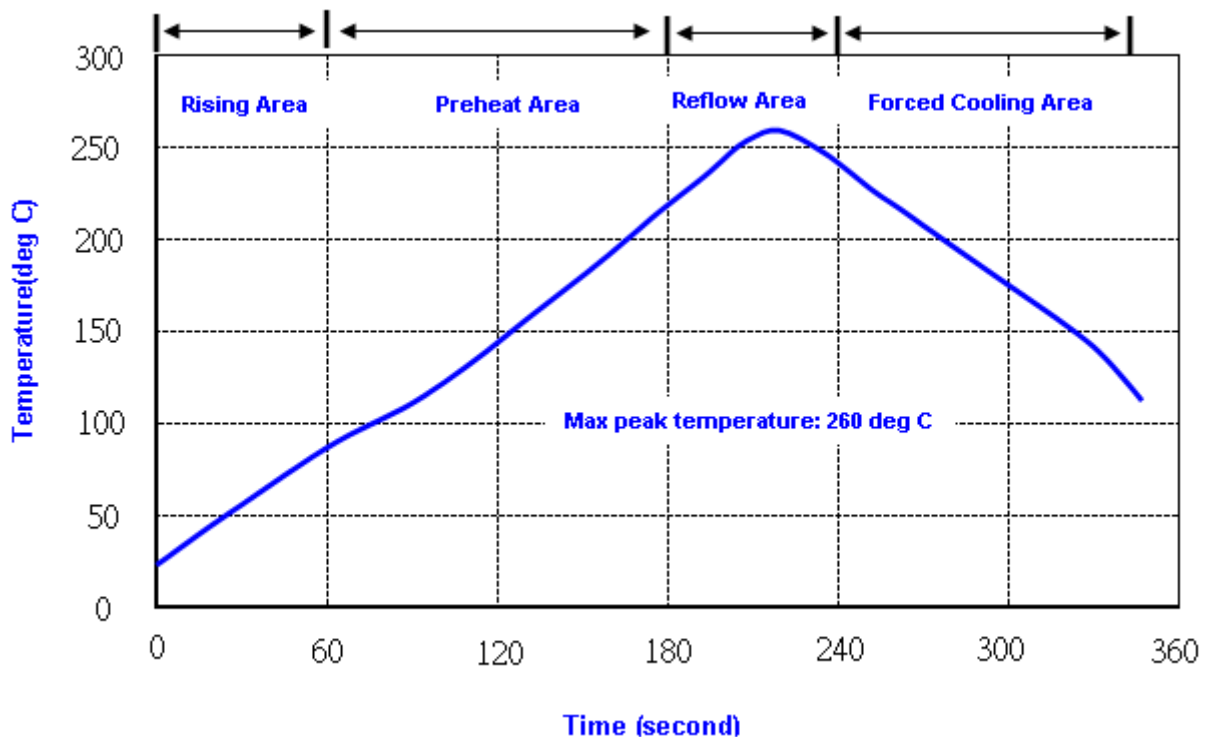
1. Unless otherwise specified tolerance on dimension ± 0.1 mm.
2. Material: conductive polystyrene with color black.
3. 10 pitch cumulative tolerance ± 0.2 mm.

Packing Quantity/Packing:

3K pcs maximum per reel



Reflow Profile:



Note: 1. Max peak temperature: 260 $\pm$ 5 deg C; Time: 10 $\pm$ 2 sec
2. Temperature: 217 $\pm$ 5 deg C; Time: 90~100 sec

Reliability Specifications

Test name	Test process / method	Reference standard
Mechanical characteristics		
resistance to Soldering heat (IR reflow)	Temp./ Duration : 265°C /10sec ×2 times Total time : 4min.(IR-reflow)	EIAJED-4701 -300(301)M(II)
Vibration	Total peak amplitude : 1.5mm Vibration frequency : 10 to 2000 Hz Sweep period : 20 minute Vibration directions : 3 mutually perpendicular Duration : 2 hr / direc.	MIL-STD 202G method 204
Mechanical Shock	directions : 3 impacts per axis Acceleration : 3000g's, +20/-0 % Duration : 0.3 ms (total 18 shocks) Waveform : Half-sine	MIL-STD 202G method 213
Solderability	Solder Temperature:265±5°C Duration time: 5±0.5 seconds.	J-STD-002
Environmental characteristics		
Thermal Shock	Heat cycle conditions -40 °C (30min) ↔ 85 °C (30min) * cycle time : 10 times	MIL-STD 883G method 1010.8
Humidity test	Temperature : 85 ± 2 °C Relative humidity : 85% Duration : 96 hours	MIL-STD 202G method 103
Dry heat (Aging test)	Temperature : 125 ± 2 °C Duration : 168 hours	MIL-STD 202G method 108A
Cold resistance (Low Temp Storage)	Temperature : -40 ± 2 °C Duration : 96 hours	IEC 60068-2-1



CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.
3. RoHS compliant from the first date of manufacture.